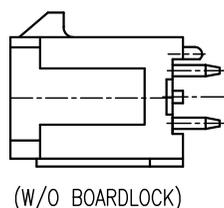
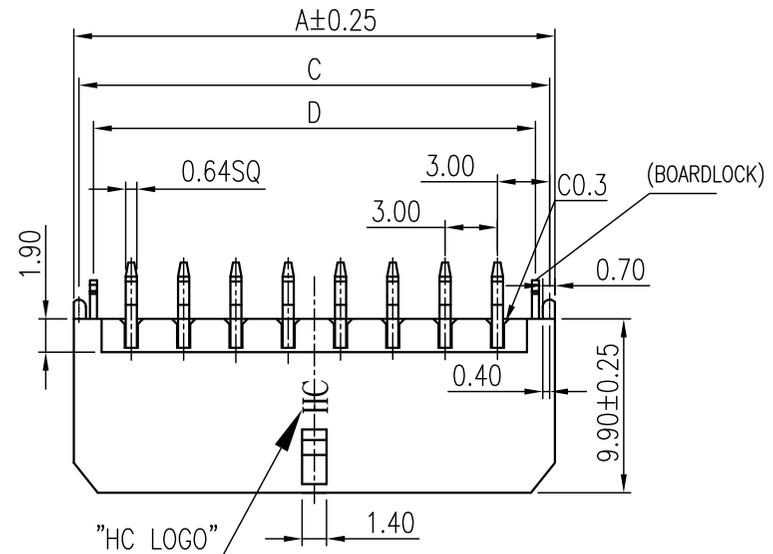


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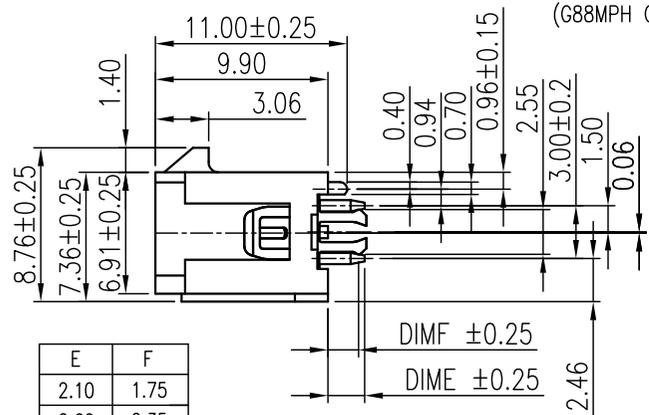
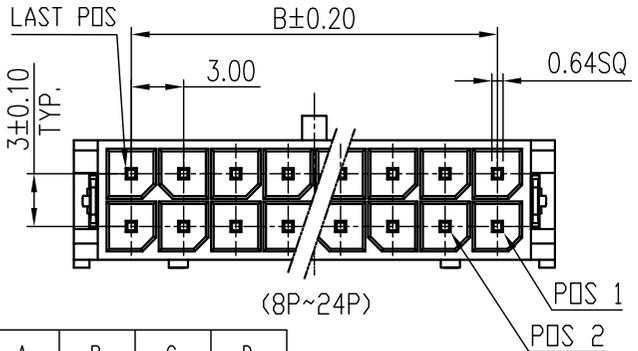
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B	NE-16287	ADD W/O BOARDLOCK OPTION/ADD TAIL 2.60,3.20,4.00,4.50 OPTION	12/14/2016	Roger Tsai
C	NE-17135	ADD BOARDLOCK LENGTH DIM F OPTION	06/19/2017	Roger Tsai
D	NE-18172	UPDATE PACKING PCS/CARTON	08/13/2018	Roger Tsai
EX1	NE-19XXX	UPDATE CONTACT FINISH TO CONTACT / SOLDERING FINISH	05/06/2019	Roger Tsai



- NOTE:
- MATERIAL
INSULATOR: HIGH TEMP. THERMOPLASTIC, OPTIONS, UL 94V-0, COLOR OPTIONS
CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.
BOARDLOCK: COPPER ALLOY.
 - FINISH:
CONTACT: SELECTIVE PLATING;
SOLDERING AREA: PLEASE REFER TO PART NO. DEFINITION.
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
BOARDLOCK:
MATTE TIN 100u" MIN. PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
 - THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
 - PACKING MUST BE PER Amphenol PACKING SPECIFICATION
 - TO ENSURE CURRENT RATING CAPABILITY, PLEASE ADOPT TOTAL SOLUTION. (G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)



- PART NO. G88MPXX1X2XXEU
- No. of CIRCUIT
- BOARD MOUNT OPTION
C: W/BOARDLOCK
D: W/O BOARDLOCK
- CONTACT / SOLDERING FINISH
0: MATTE TIN 100 μ"(OVERALL)
UNDER PLATING NICKEL 50 μ"
THICKNESS MIN
1: FLASH GOLD / FLASH GOLD
2: 15 μ" GOLD/ MATTE TIN 100 μ"
3: 30 μ" GOLD/ MATTE TIN 100 μ"
- INSULATOR, TAIL (DIM E)
BLANK: LCP (BLACK), 2.10MM
1: LCP (NATURAL), 2.10MM
2: LCP (BLACK), 2.60MM
3: LCP (NATURAL), 2.60MM
4: LCP (BLACK), 3.20MM
5: LCP (NATURAL), 3.20MM
6: LCP (BLACK), 4.00MM
7: LCP (NATURAL), 4.00MM
8: LCP (BLACK), 4.50MM
9: LCP (NATURAL), 4.50MM

E	F
2.10	1.75
2.60	2.35
3.20	2.95
4.00	3.85
4.50	4.25

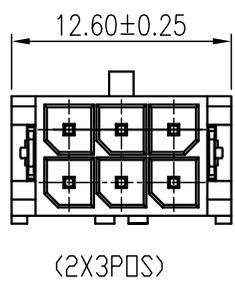
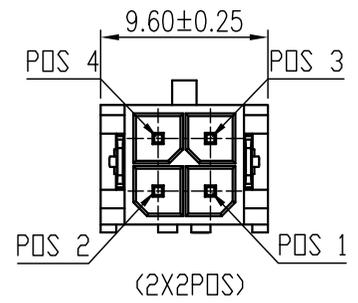
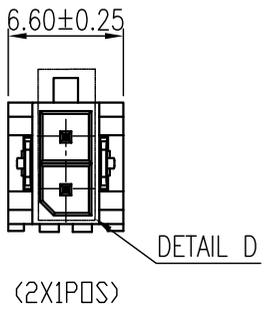
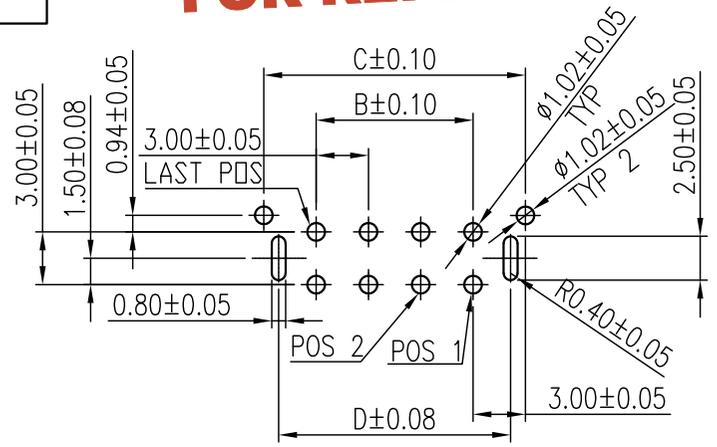
POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

TOLERANCE	APPROVALS	DATE	TITLE		PART No.	
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10	DRAWN Juda Liu	05/06/2019	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		Amphenol ® Amphenol Corporation Amphenol Taiwan Corporation	
ANGULAR ±1°	CHECKED Debby Hung	05/06/2019				
UNLESS OTHERWISE SPECIFIED	APPROVED Roger Tsai	05/06/2019				
	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G88MPXX1X2XXEU	
			SCALE NA	SHEET 1 OF 4	DWG No. G88MPXX1X2XXEU	
					REV. EX1	

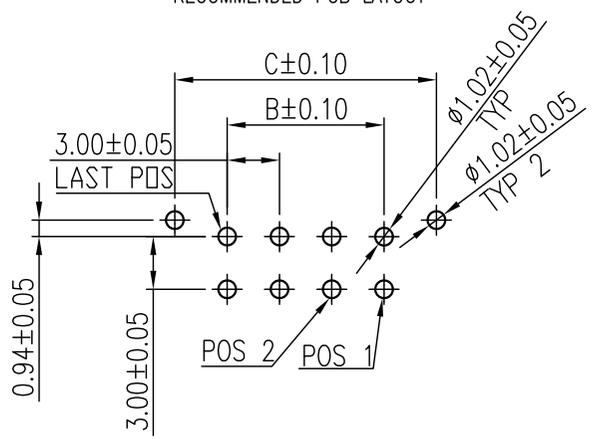
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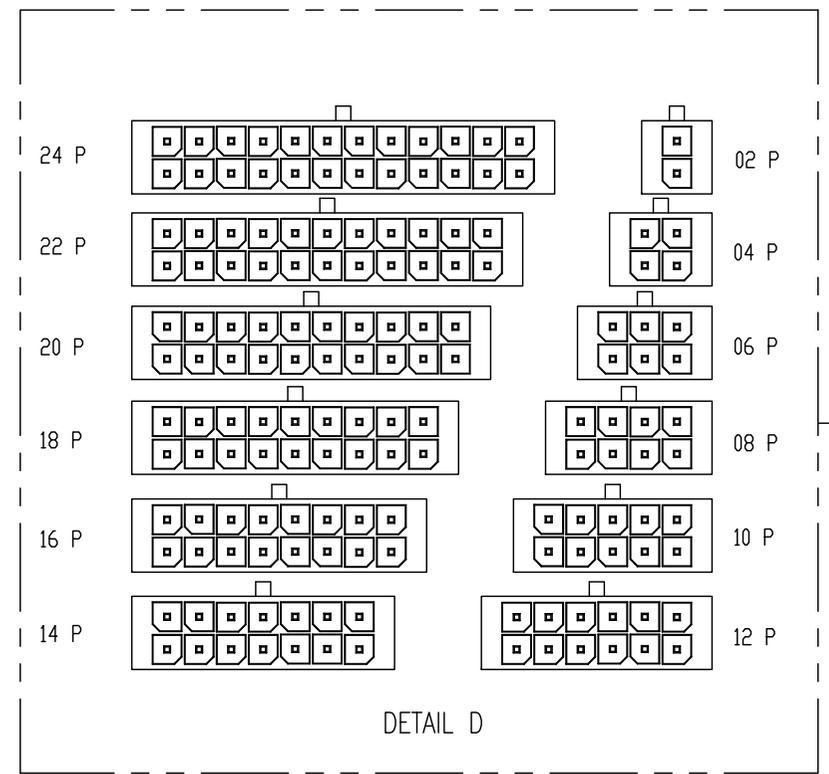
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02~24P (W/BOARDLOCK)
RECOMMENDED PCB LAYOUT



02~24P (W/O BOARDLOCK)
RECOMMENDED PCB LAYOUT



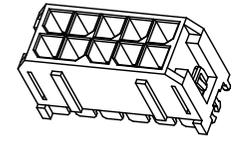
TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®]		
X.		DRAWN	Juda Liu	05/06/2019	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		Amphenol Corporation Amphenol Taiwan Corporation		
X.X	±0.30	CHECKED	Debby Hung	05/06/2019					
X.XX	±0.20	APPROVED	Roger Tsai	05/06/2019					
X.XXX	±0.10	DWG TYPE		PROJECT CODE			UNIT	SIZE	PART No.
ANGULAR	±1°	CUST DWG		PHD			mm	A3	G88MPXX1X2XXEU
UNLESS OTHERWISE SPECIFIED					SCALE	SHEET	DWG No.		REV.
					NA	2 OF 4	G88MPXX1X2XXEU		EX1

FOR REFERENCE ONLY

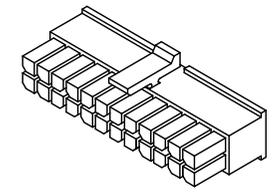
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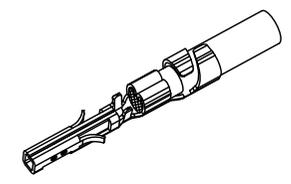
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021X2XXEU	G88MPH0222CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041X2XXEU	G88MPH0422CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061X2XXEU	G88MPH0622CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081X2XXEU	G88MPH0822CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101X2XXEU	G88MPH1022CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121X2XXEU	G88MPH1222CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141X2XXEU	G88MPH1422CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161X2XXEU	G88MPH1622CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181X2XXEU	G88MPH1822CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201X2XXEU	G88MPH2022CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221X2XXEU	G88MPH2222CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241X2XXEU	G88MPH2422CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



AMPHENOL CABLE HOUSING



AMPHENOL CABLE TERMINAL

NOTE:
TO ENSURE CURRENT RATING CAPABILITY, PLEASE ADOPT TOTAL SOLUTION.
(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®]						
X.		DRAWN		Juda Liu	05/06/2019	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		Amphenol Corporation					
X.X	±0.30	CHECKED		Debby Hung	05/06/2019		UNIT	mm	SIZE	A3	PART No.	G88MPXX1X2XXEU	
X.XX	±0.20	APPROVED		Roger Tsai	05/06/2019		SCALE	NA	SHEET	3 OF 4		DWG No.	G88MPXX1X2XXEU
X.XXX	±0.10	UNLESS OTHERWISE SPECIFIED		CUST DWG		PROJECT CODE	PHD				REV.	EX1	

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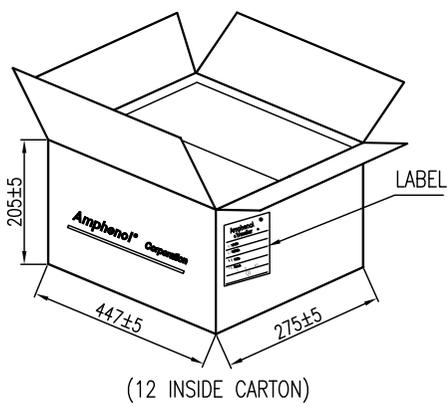
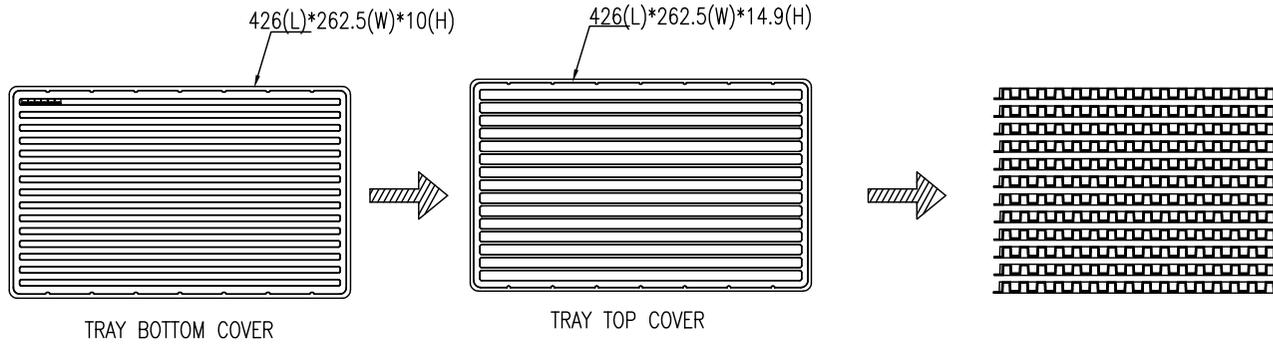


TABLE A: TAIL (DIM E) < 4.00mm

POS	PCS/TRAY	PCS/CARTON
2	900	10800
4	615	7380
6	465	5580
8	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

TABLE B: TAIL (DIM E) ≥ 4.00mm

POS	PCS/TRAY	PCS/CARTON
2	840	10080
4	574	6888
6	434	5208
8	350	4200
10	294	3528
12	252	3024
14	224	2688
16	196	2352
18	168	2016
20	154	1848
22	140	1680
24	140	1680

NOTE:
1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
3. THICKNESS : 0.80±0.05mm.

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation							
X.		DRAWN	Juda Liu	05/06/2019	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		UNIT	mm	SIZE	A3	PART No.	G88MPXX1X2XXEU		
X.X	±0.30	CHECKED	Debby Hung	05/06/2019			SCALE	NA	SHEET	4 OF 4		DWG No.	G88MPXX1X2XXEU	
X.XX	±0.20	APPROVED	Roger Tsai	05/06/2019			PROJECT CODE		PHD		REV.	EX1		
X.XXX	±0.10	UNLESS OTHERWISE SPECIFIED		CUST DWG										